WL1835MOD C2PC Details

Revision 2.0

January 22, 2018

Revision Control

Author Name	Description	Revision	Date
Rizwan Murji	Initial Draft	1.0	Oct 31, 2017

1. Introduction

The purpose of this document is to request a C2PC on our existing WL18MODGB modular certification (FCC ID: Z64 - WL18SBMOD, ISED ID: 451I-WL18SBMOD, test grades 01, 05, 31 and 35). The change will be to the OEM installation instructions to include a minimum cable loss. The parts in question can be seen below:

2. Summary

Our original filing was done with the WL18MODGB placed on the WL1835MOCOM8B evaluation board. The trace loss from the output of the main antenna to the U.FL connector is 1dBm as show in Figure 1 below.
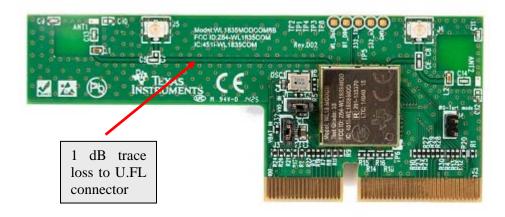
1 dB trace loss to U.FL connector

Figure 1: WL18MODGB mounted on WL1835MODCOM8B EVM

Testing was also performed with the WL18MODGB Test grade 35 placed on the WL1837MODCOM8I evaluation board. During the testing a 1dB cable loss was included in the measurements as shown in Figure 2. Results of the test (to be supplied by Sporton) show no measureable difference in output power as the original grant.
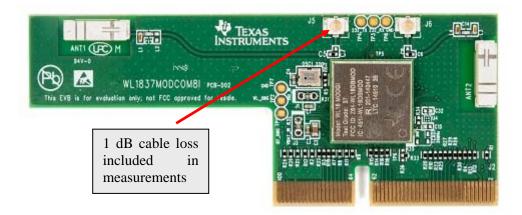

1 dB cable loss included in measurements

Figure 2: WL18MODGB mounted on WL1837MODCOM8B EVM

Based on the above information we are requesting that a C2PC be performed allowing customers to include an equivalent 1dB loss of any shape or form (such as trace, cable or 1-dB pi-pad loss) in their design and maintain the use of the current FCC and ISED IDs. The integrator guide provided to customers will be updated to reflect this with the following statement:

Note: at least an equivalent 1dB loss (in the form of trace, cable or 1-dB pi-pad loss) is required between the output of the WL18MODGB module and the U.FL connector to be compliant with the current Z64-WL18SBMOD and 451I-WL18SBMOD module certification.

Important Notice

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE–SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, the customer to minimize inherent or procedural hazards must provide adequate design and operating safeguards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.